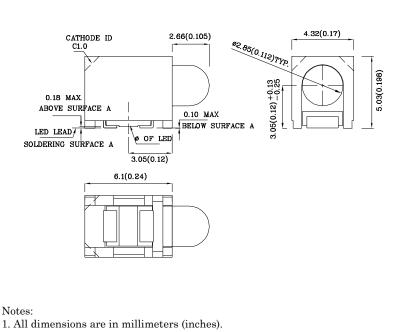


SINGLE LEVEL SURFACE MOUNT CBI

- •Surface mount type
- $\bullet {\rm Compatible}$  with automatic placement equipment
- $\bullet {\rm Compatible}$  with infrared and vapor phase solder processes
- $\bullet Black \ case \ enhances \ contrast \ ratio$
- $\bullet {\rm Housing}$  material meets UL94V-0 flammability rating
- $\bullet {\rm Lens}$  material meets UL94-HB flammability rating
- •MSL (Moisture Sensitivity Level): 4
- $\bullet RoHS$  compliant





- 2. Tolerance is  $\pm 0.25(0.01")$  unless otherwise noted.
- 3. Specifications are subject to change without notice.

Operating Characteristics (T <sub>A</sub> =25°C)		MR (GaAlAs)	Unit
Forward Voltage (Typ.) (I <sub>F</sub> =10mA)	$V_{\rm F}$	1.8	V
Forward Voltage (Max.) (I <sub>F</sub> =10mA)	$V_{\rm F}$	2.5	V
Reverse Current (Max.) (V <sub>R</sub> =5V)	$I_R$	10	uA
Wavelength of Peak Emission CIE127-2007*(Typ.) (I <sub>F</sub> =10mA)	λΡ	655*	nm
Wavelength of Dominant Emission CIE127-2007*(Typ.) (I <sub>F</sub> =10mA)	λD	640*	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I <sub>F</sub> =10mA)	$ riangle\lambda$	20	nm
Capacitance (Typ.) (V <sub>F</sub> =0V, f=1MHz)	С	45	$_{ m pF}$

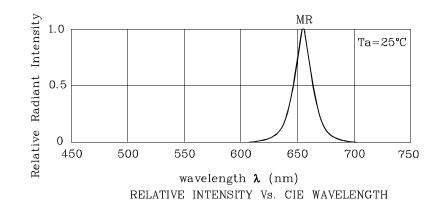
Part Number	Emitting Color	Emitting Material	Lens-color	CIE127	s Intensity 7-2007* 0mA) cd	Wavelength CIE127-2007* nm λP	Viewing Angle 20 1/2
				min.	typ.		
XPR1ZMR45S	Red	GaAlAs	Water Clear	8*	17*	655*	50°

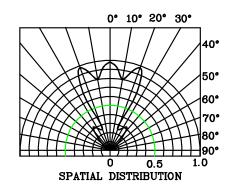
\*Luminous intensity value and wavelength are in accordance with CIE127-2007 standards.

May 23, 2014

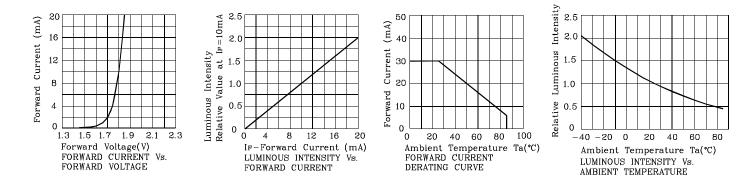
Absolute Maximum Ratings (T <sub>A</sub> =25°C)		MR (GaAlAs)	Unit	
Reverse Voltage	$V_{R}$	5	V	
Forward Current	$\mathbf{I}_{\mathbf{F}}$	30	mA	
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	$i_{\rm FS}$	155	mA	
Power Dissipation	$\mathbf{P}_{\mathbf{D}}$	75	mW	
Operating Temperature	$T_{\rm A}$	-40 ~ +85	°C	
Storage Temperature	Tstg	-40 ~ +100	U	





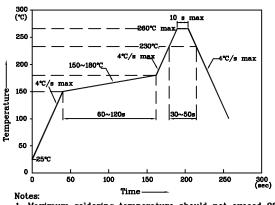


♦ MR



# LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

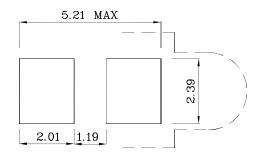


- 1. Maximum soldering temperature should not exceed 260°C
- 2. Recommended reflow temperature: 145°C-260°C 3. Do not put stress to the epoxy resin during
- high temperatures conditions

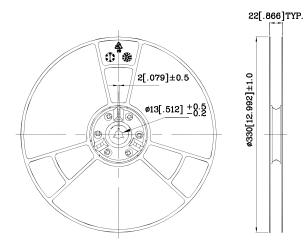


Recommended Soldering Pattern

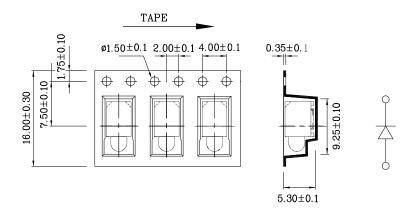
(Units : mm; Tolerance: ± 0.1)



## Reel Dimension



## Tape Specification (Units : mm)



### Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength),

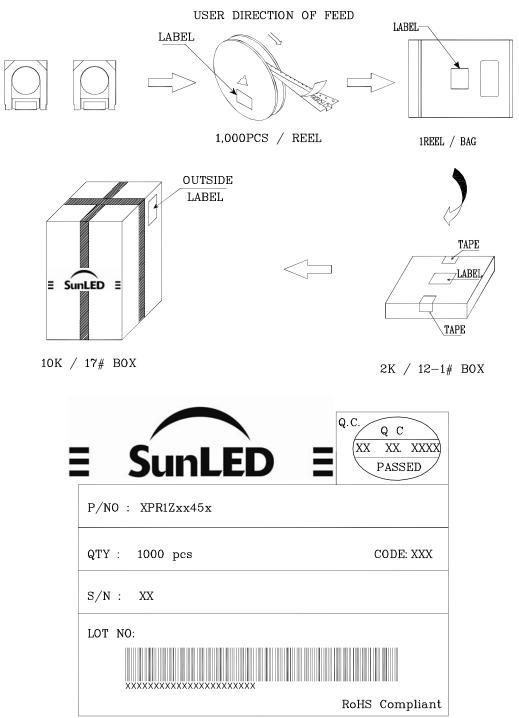
the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous intensity / luminous flux: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.



## PACKING & LABEL SPECIFICATIONS



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- 1. Data presented in this document reflect statistical figures and should be treated as technical reference only.
- 2. Contents within this document are subject to improvement and enhancement changes without notice.
- 3. The product(s) in this document are designed to be operated within the electrical and environmental specifications indicated on the datasheet.
- User accepts full risk and responsibility when operating the product(s) beyond their intended specifications.
- 4. The product(s) described in this document are intended for electronic applications in which a person's life is not reliant upon the LED. Please consult with a SunLED representative for special applications where the LED may have a direct impact on a person's life.
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- 6. Additional technical notes are available at http://www.SunLEDusa.com/TechnicalNotes.asp